

Astek Corporation
P/N: 70-923300-A

		Before Press	After Press	
PADS				
N7000-2 HT	1	0.0006	0.0014	1/2 OZ + PLATING
		0.008	0.008	POLY
POWER	2	0.0006	0.0006	1/2 OZ CU
N7000-3		0.0033	0.003	1080 PREPREG
GND	3	0.0006	0.0006	1/2 OZ CU
N7000-2 HT		0.008	0.008	POLY
N7000-3		0.0033	0.003	1080 PREPREG
N7000-3		0.0033	0.003	1080 PREPREG
SIGNAL		0.0006	0.0006	1/2 OZ CU, Zo = 100 Ohms +/- 10%
TICER 50 OHM SQ.		0.0006	0.0006	TICER FOIL / R = 100 Ohms +/-20%
N7000-2 HT		0.008	0.008	POLY
PADS		0.0006	0.0014	1/2 OZ + PLATING
		0.0375		Thickness Before Lamination
		0.0382		Thickness Out Of Lamination

***NOTE: Need to verify that power planes will fit on one layer (layer 2)

NOTES:

1. PCB SHALL BE FABRICATED TO IPC-6011 AND 6012 CLASS 2 OR BETTER
2. MATERIAL AS DEFINED IN STACK-UP DRAWING
3. FINISHED THICKNESS: 0.039 +/- 0.007"
4. FINISH: 30 MICRO INCH GOLD PLATING OVER 50 MICRO INCH NICKEL UNDERPLATE
5. SOLDER MASK: GREEN LPI PER IPC-SM-840-C, CLASS T
SOLDER MASK CLEARANCE PADS IN GERBER DATA ARE THE SAME SIZE AS COPPER PADS. VENDOR MAY CREATE CLEARANCES TO FIT YOUR PROCESSES UP TO 0.004" CLEARANCE. SIDES: TOP AND BOTTOM LAYERS
6. SILKSCREEN: NON-CONDUCTIVE WHITE EPOXY BASED INK; NOT ALLOWED ON COMPONENT PADS OR IN MOUNTING HOLES.
7. 6 MIL HOLES ARE VIA_IN_PAD AND SHALL BE FILLED AND FINISHED.
8. HOLE SIZES AFTER PLATING AND FINAL CONDUCTOR FINISH SHALL BE PER DRILL TABLE ON DRILL DRAWING. CENTERLINE OF HOLES SHALL BE WITHIN 0.005" RADIAL OF EXACT CENTERLINE OF THE PAD ON THE ARTWORK.
9. 100% TESTING FOR OPENS AND SHORTS REQUIRED.
10. PERFORM GERBER FILE DATABASE DESIGN RULE CHECK.
11. IMPEDANCE REQUIREMENTS AS SHOWN IN LAYER STACK-UP DRAWING.
VENDOR MAY ADJUST TRACE SIZE OR LAYER THICKNESS AS NECESSARY TO ACHIEVE THE IMPEDANCE REQUIREMENTS.
12. VENDOR MAY ALTER PHOTO DATA (GERBER) TO COMPENSATE FOR ETCHING PROCESS
13. ALL IMPEDANCE COUPONS MUST BE SERIALIZED TO INDICATE WHICH BOARD THEY CORRESPOND TO. ALL IMPEDANCE COUPONS TO BE SUPPLIED WITH BOARDS.
14. BURIED RESISTOR VALUE: 100 OHMS +/- 20%; TICER 50 OHMS PER SQUARE
15. SOLDERABILITY TEST, CATEGORY 2 OF J-STD-003 OR STRESSED MICROSECTION



Astek Corporation
 5055 Corporate Plaza Drive
 Colorado Springs, CO 80919
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ENGINEER: Steve Wint

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DATE:	9/7/2012	SHEET	1 OF 2